



## N And P- Channel Enhancement Mode Power MOSSFET

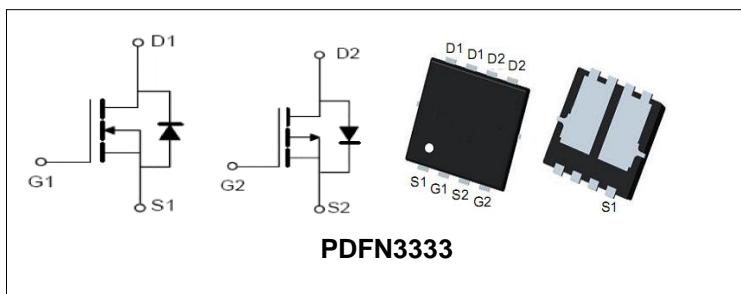
## Features

- Improved dv/dt Capability, High Ruggedness
- Maximum Junction Temperature Range (150°C)

## Applications

- DC Fan
- Brushless motor
- Optimized for Power Management Applications for Portable Products, such as H-bridge, Inverters Car Charger and Others

N-Channel		
BVDSS	30	V
ID	15	A
RDS(on)@VGS=10V	16	mΩ
RDS(on)@VGS=4.5V	21	mΩ



P-Channel		
BVDSS	-30	V
ID	-11	A
RDS(on)@VGS=-10V	26	mΩ
RDS(on)@VGS=-5V	37	mΩ

## Order Information

Product	Package	Marking	Reel Size	Reel	Carton
PTQ15C03	PDFN3333	PTQ15C03	13inch	5000PCS	50000PCS

## Absolute Maximum Ratings

Symbol	Parameter	N-Channel	P-Channel	Unit	
<b>Common Ratings (TC=25°C Unless Otherwise Noted)</b>					
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	30	-30	V	
V <sub>GS</sub>	Gate-Source Voltage	±20	±20	V	
T <sub>J</sub>	Maximum Junction Temperature	150		°C	
T <sub>STG</sub>	Storage Temperature Range	-50 to 150		°C	
I <sub>S</sub>	Diode Continuous Forward Current	TC =25°C	15	-11	A
<b>Mounted on Large Heat Sink</b>					
I <sub>DM</sub>	Pulse Drain Current Tested (Sillicon Limit) (Note1)	TC =25°C	60	-44	A
I <sub>D</sub>	Continuous Drain current	TC=25°C	15	-11	A
P <sub>D</sub>	Maximum Power Dissipation	TC =25°C	15		W
R <sub>θJC</sub>	Thermal Resistance Junction-to-Case (Note2)		8.3		°C/W



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## N-Channel Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ TJ = 25°C (unless otherwise stated)</b>						
$V_{(BR)DSS}$	Drain- Source Breakdown Voltage	$VGS=0V$ $ID=250\mu A$	30	--	--	V
$I_{DSS}$	Zero Gate Voltage Drain current	$VDS=30V, VGS=0V$	--	--	1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$VGS=\pm 20V, VDS=0V$	--	--	$\pm 100$	nA
$V_{GS(TH)}$	Gate Threshold Voltage	$VDS=VGS, ID=250\mu A$	1	1.5	2.5	V
$R_{DS(ON)}$	Drain-Source On-State Resistance (Note3)	$VGS=10V, ID=10A$	--	16	22	$m\Omega$
		$VGS=4.5V, ID=6A$	--	21	31	$m\Omega$
<b>Dynamic Electrical Characteristics @ TJ = 25°C (unless otherwise stated) (Note4)</b>						
$C_{iss}$	Input Capacitance	$VDS= 15V,$ $VGS=0V,$ $F=1MHz$	--	584	--	pF
$C_{oss}$	Output Capacitance		--	112	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	96	--	pF
$Q_g$	Total Gate Charge	$VDS= 15V,$ $ID= 10A,$ $VGS= 10V$	--	15	--	nC
$Q_{gs}$	Gate-Source Charge		--	4.7	--	nC
$Q_{gd}$	Gate-Drain Charge		--	3.6	--	nC
<b>Switching Characteristics (Note4)</b>						
$t_{d(on)}$	Turn-on Delay Time	$VDD= 30V,$ $ID=10A,$ $VGEN=10V,$ $RG=3\Omega$	--	5	--	nS
$t_r$	Turn-on Rise Time		--	8	--	nS
$t_{d(off)}$	Turn-off Delay Time		--	21	--	nS
$t_f$	Turn-off Fall Time		--	7	--	nS
<b>Source- Drain Diode Characteristics@ TJ = 25°C (unless otherwise stated)</b>						
$V_{SD}$	Forward on voltage	$IS=15A, VGS=0V$	--	0.82	1.2	V



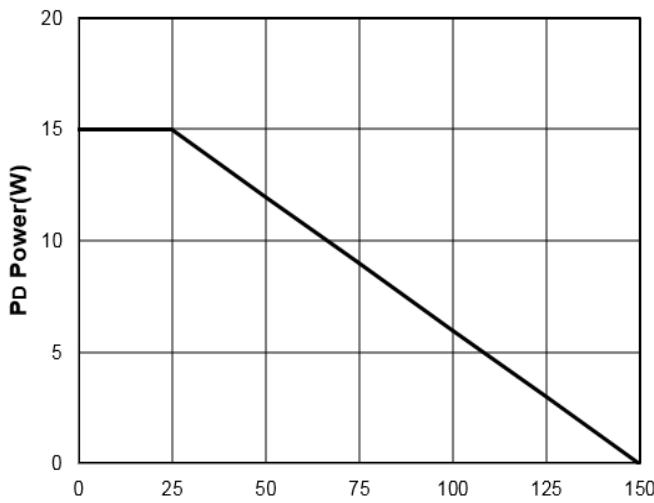
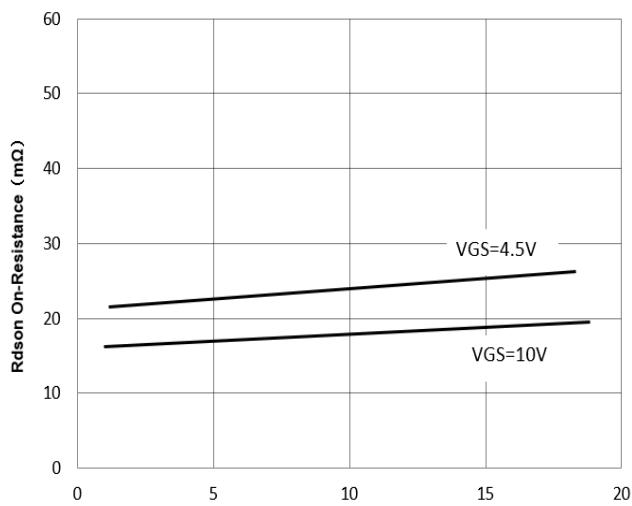
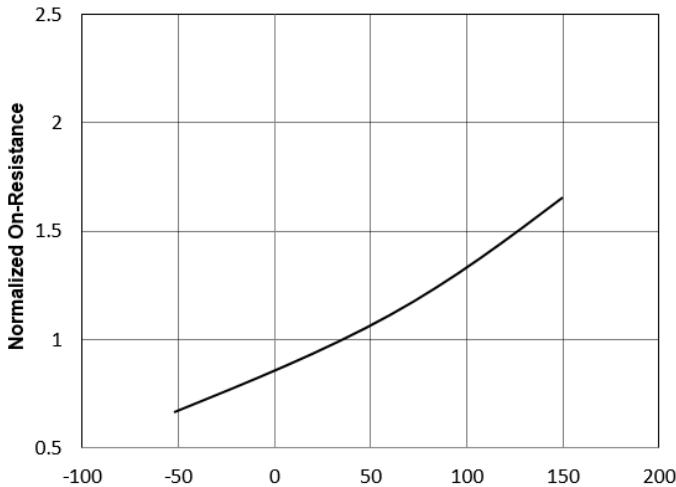
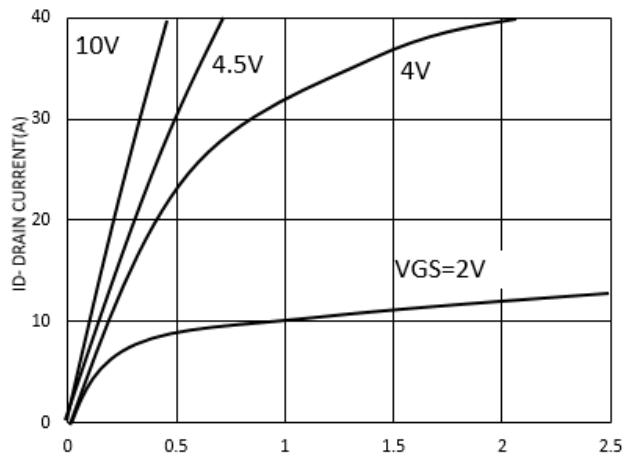
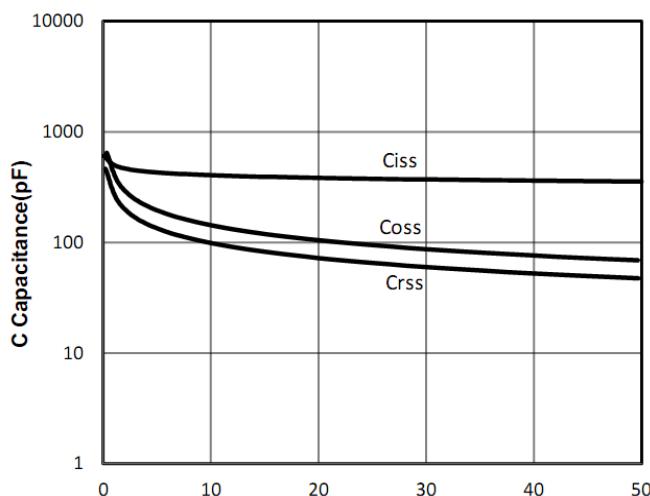
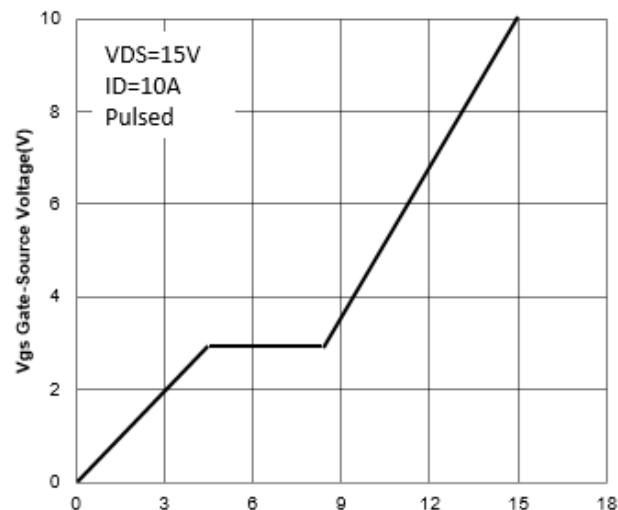
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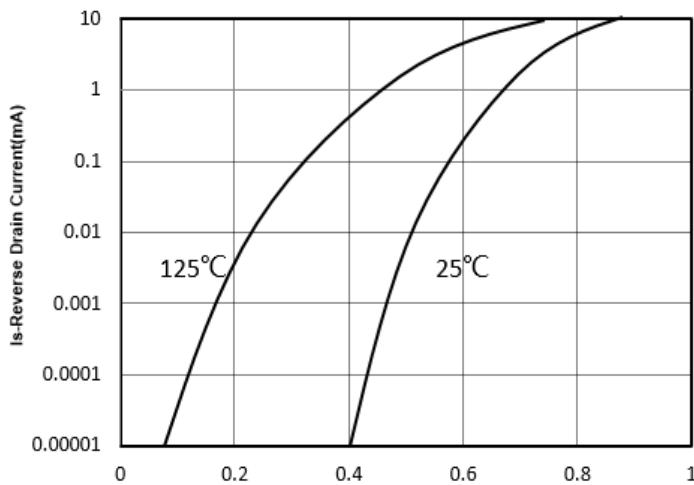
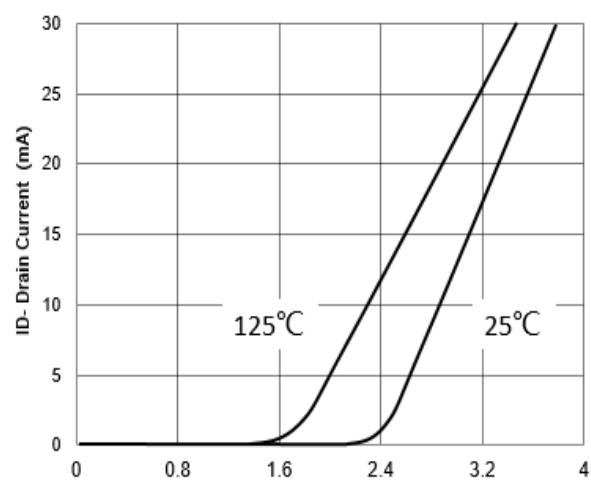
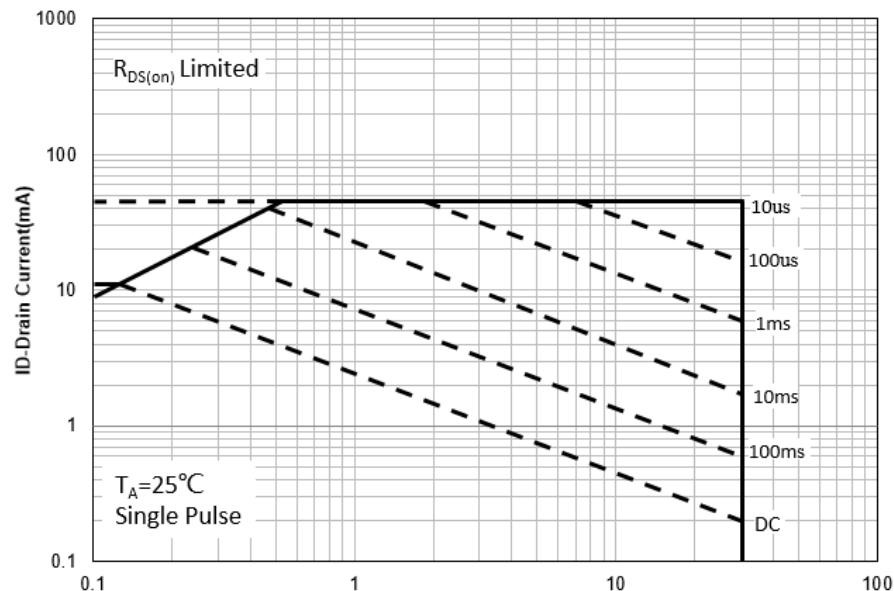
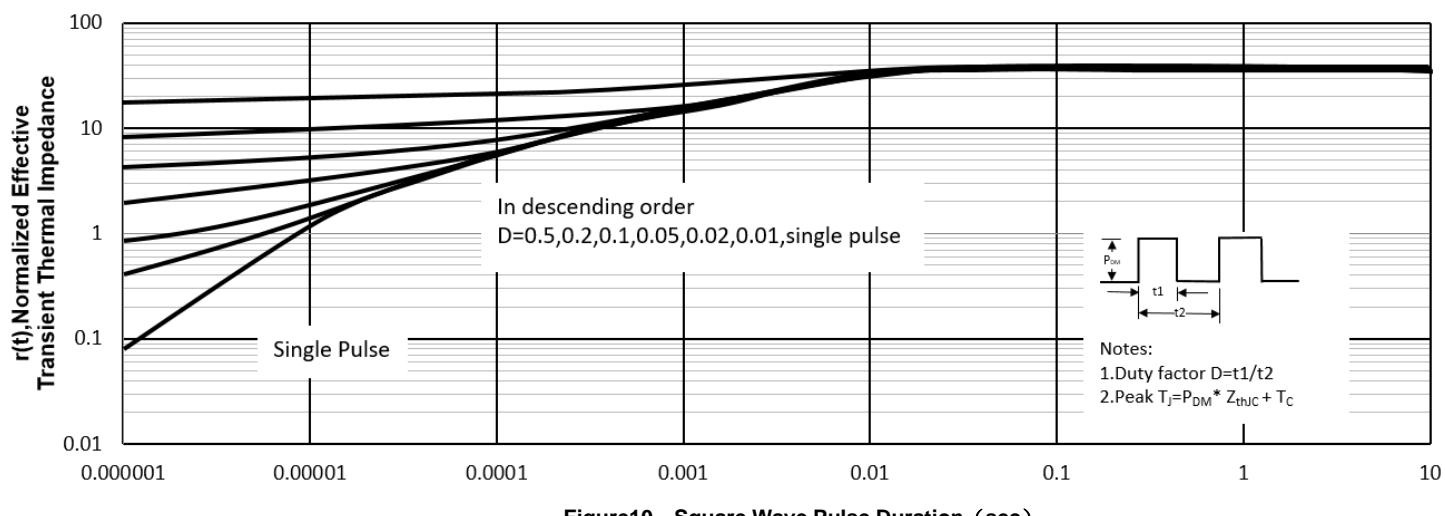
## P-Channel Electrical Characteristics

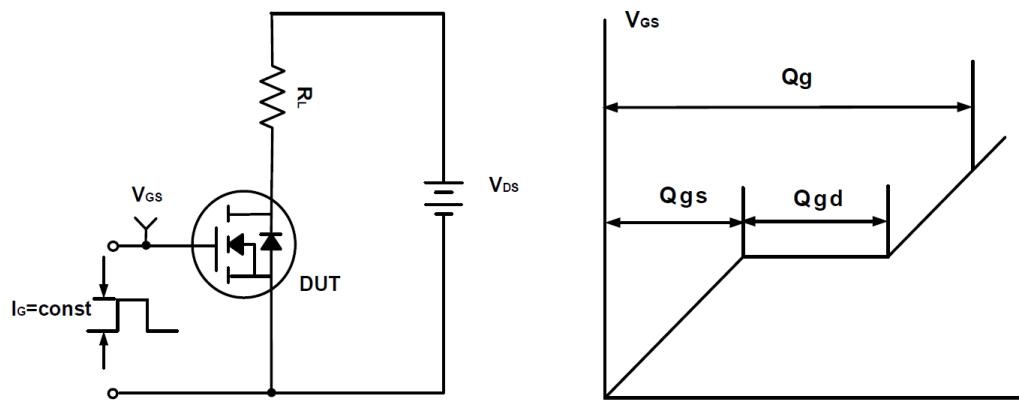
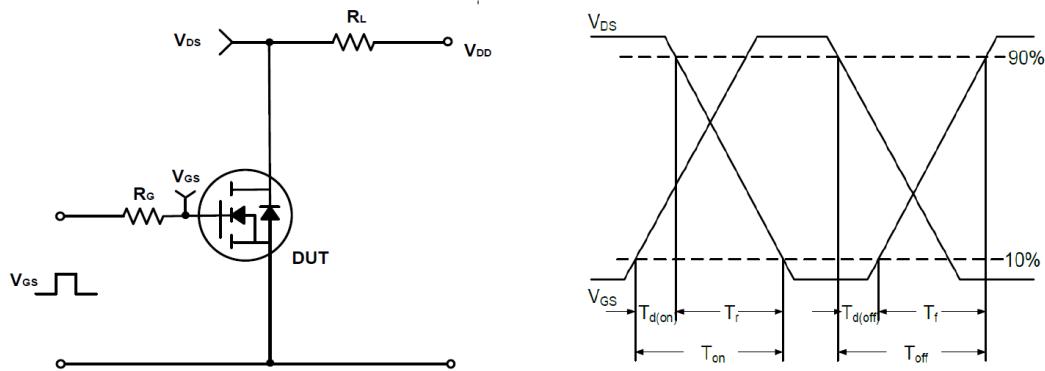
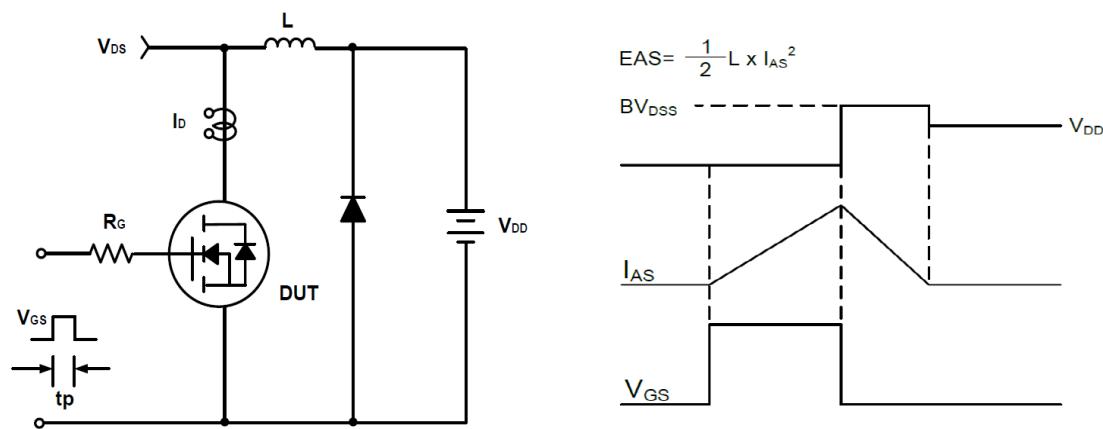
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{(\text{BR})\text{DSS}}$	Drain- Source Breakdown Voltage	$V_{GS}=0\text{V}$ $ID=250\mu\text{A}$	-30	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain current	$V_{DS}=-30\text{V}, V_{GS}=0\text{V}$	--	--	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	$\pm 100$	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, ID=250\mu\text{A}$	-1.0	-1.5	-2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance (Note3)	$V_{GS}=-10\text{V}, ID=-8\text{A}$	--	26	34	$\text{m}\Omega$
		$V_{GS}=-5\text{V}, ID=-5\text{A}$	--	37	46	$\text{m}\Omega$
<b>Dynamic Electrical Characteristics @ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated) (Note4)</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{DS} = -15\text{V},$ $V_{GS} = 0\text{V},$ $F = 1\text{MHz}$	--	1200	--	pF
$C_{\text{oss}}$	Output Capacitance		--	155	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	139	--	pF
$Q_g$	Total Gate Charge	$V_{DS} = -15\text{V},$ $ID = -8\text{A},$ $V_{GS} = -10\text{V}$	--	52	--	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	9.8	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	8.3	--	nC
<b>Switching Characteristics (Note4)</b>						
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{DD} = -15\text{V},$ $ID = -1\text{A},$ $V_{GS} = -10\text{V},$ $RG = 6\Omega$	--	13	--	nS
$t_r$	Turn-on Rise Time		--	15	--	nS
$t_{\text{d(off)}}$	Turn-off Delay Time		--	198	--	nS
$t_f$	Turn-off Fall Time		--	98	--	nS
<b>Source- Drain Diode Characteristics@ <math>T_J = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
$V_{\text{SD}}$	Forward on voltage	$IS = -11\text{A}, V_{GS} = 0\text{V}$	--	-0.8	-1.2	V

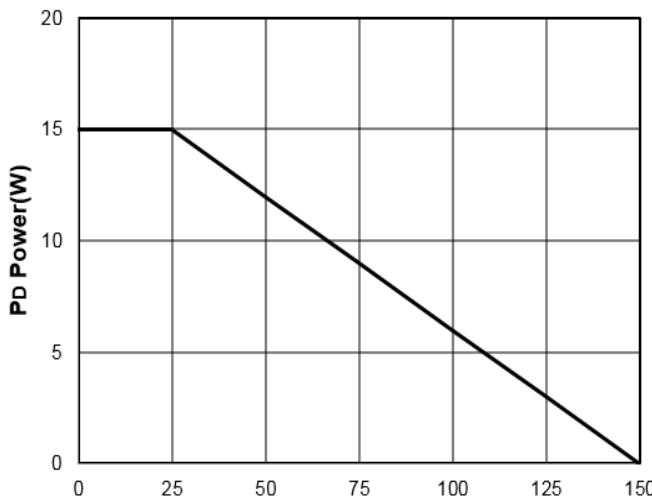
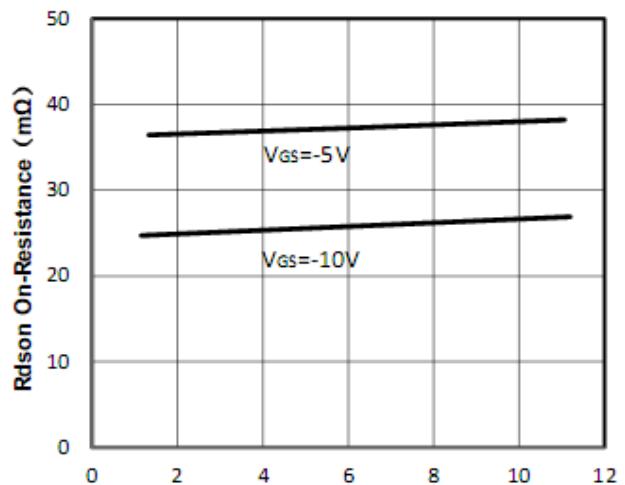
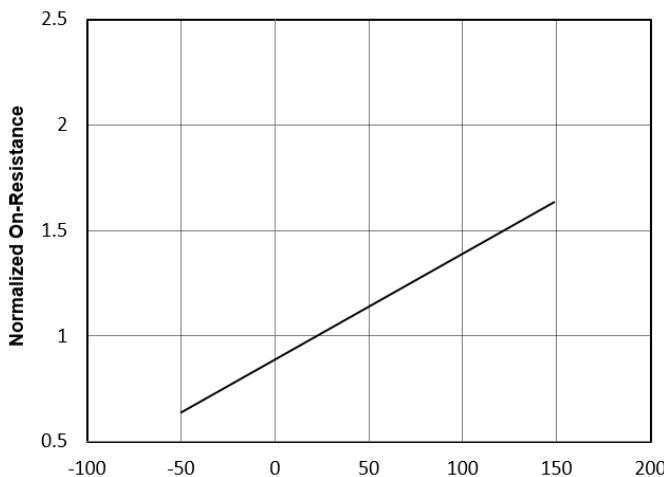
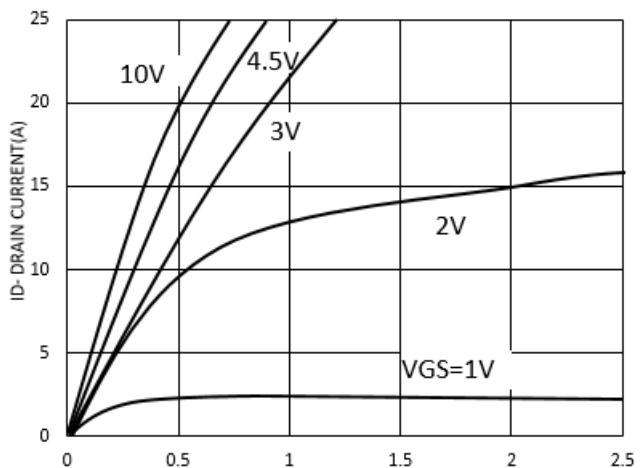
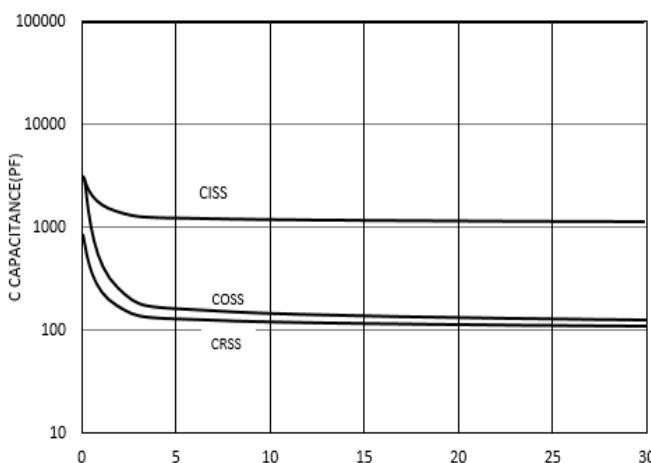
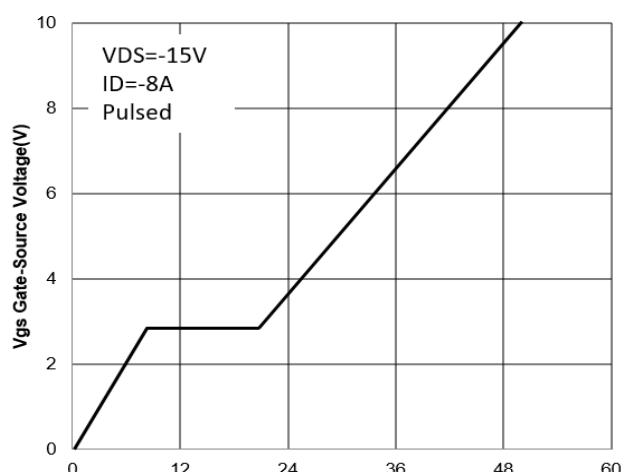
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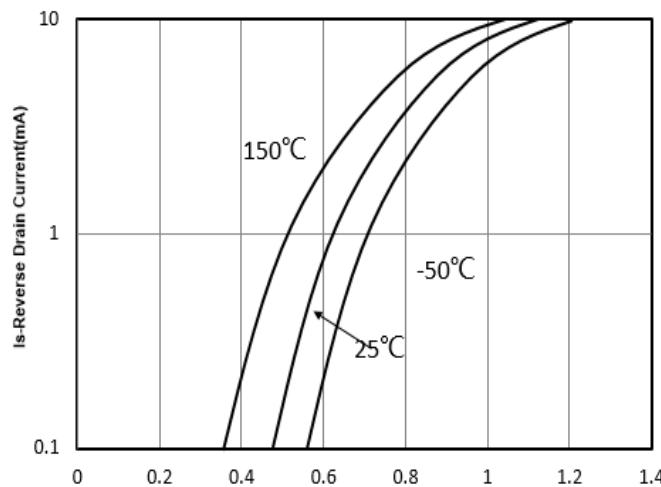
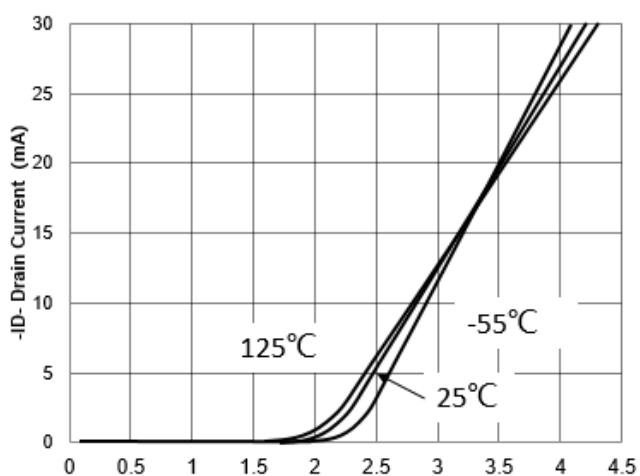
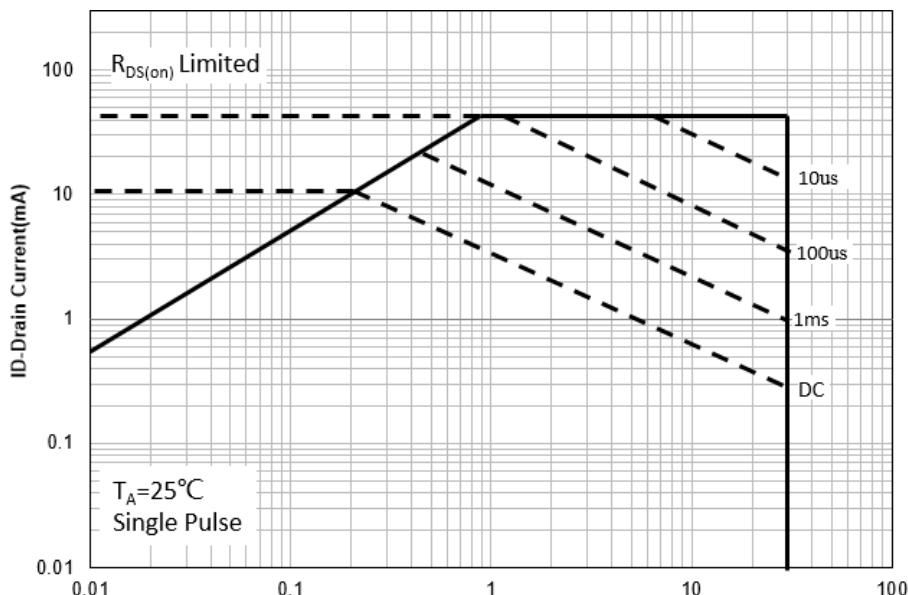
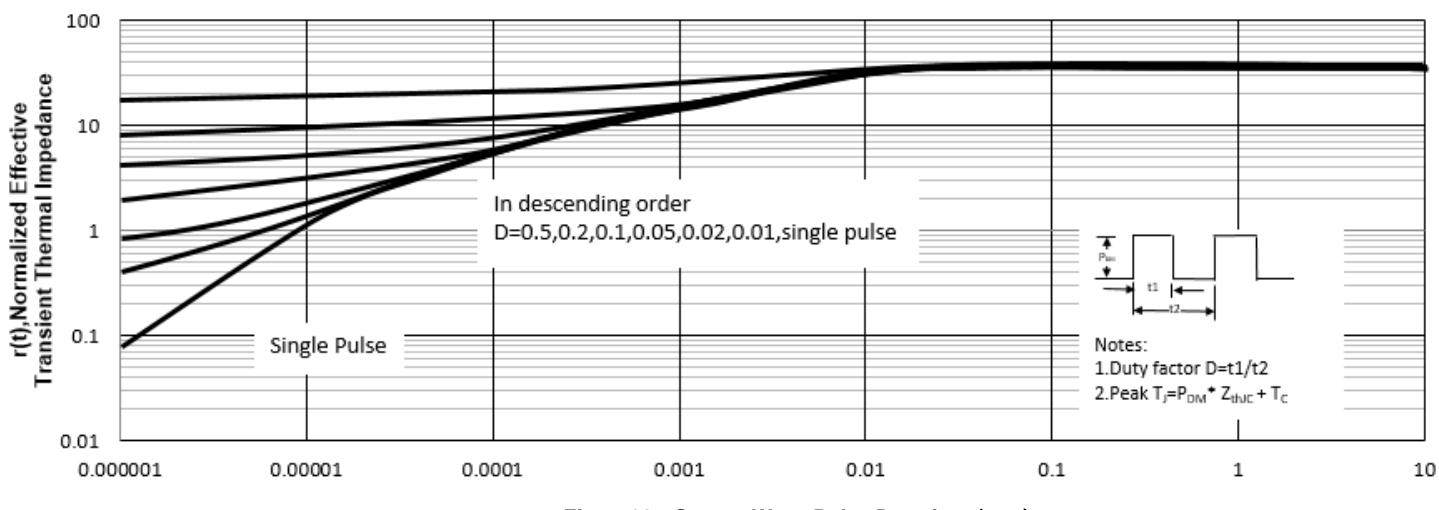
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec
3. Pulse Test: pulse width  $\leq 300$  us, duty cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production testing.

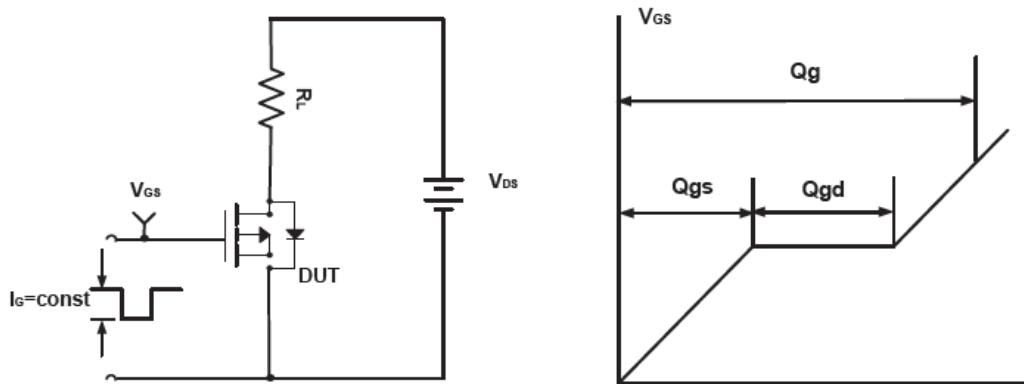
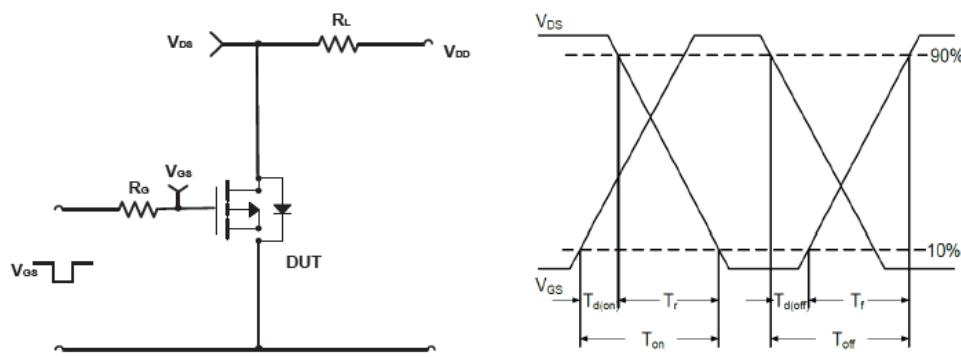
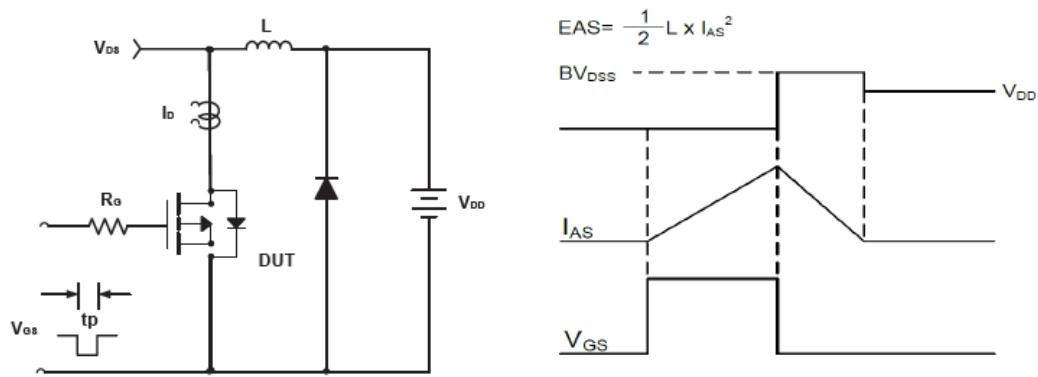
**N And P- Channel Enhancement Mode Power MOSSFET  
Typical Characteristics (N-Channel)**

**Figure1: T<sub>J</sub> Junction Temperature (°C)**

**Figure2: I<sub>D</sub> Drain Current (A)**

**Figure3: T<sub>J</sub> Junction Temperature (°C)**

**Figure4: V<sub>DS</sub> Drain-Source Voltage (V)**

**Figure5: V<sub>DS</sub> Drain-Source Voltage (V)**

**Figure6: Q<sub>g</sub> Gate Charge (nC)**

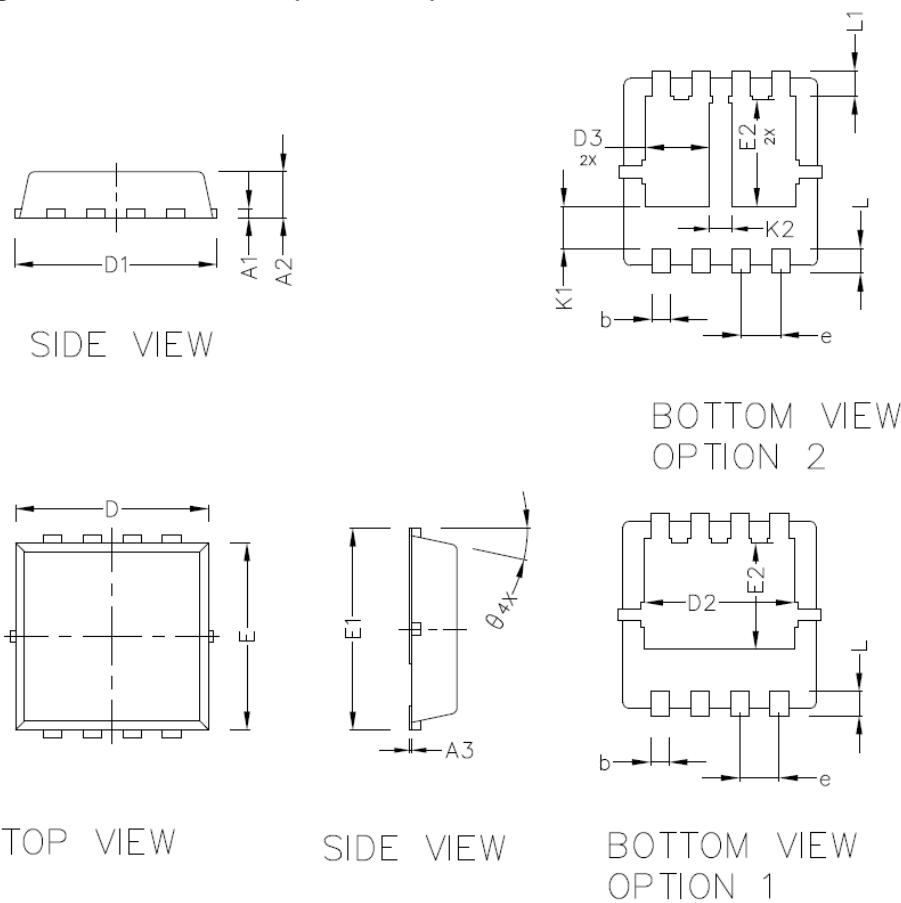
**N And P- Channel Enhancement Mode Power MOSSFET**

**Figure7: Vsd Source-Drain Voltage (V)**

**Figure8: Vgs Gate-Source Voltage (V)**

**Figure9: Vds Drain -Source Voltage (V)**

**Figure10: Square Wave Pulse Duration (sec)**

**N And P- Channel Enhancement Mode Power MOSSFET**
**Test Circuit and Waveform(N-Channel):**

**Figure A Gate Charge Test Circuit & Waveforms**

**Figure B Switching Test Circuit & Waveforms**

**Figure C Unclamped Inductive Switching Circuit & Waveforms**

**N And P- Channel Enhancement Mode Power MOSSFET**
**Typical Characteristics(P-Channel)**

**Figure11: T<sub>J</sub> Junction Temperature (°C)**

**Figure12: -Id Drain Current (A)**

**Figure13: T<sub>J</sub> Junction Temperature (°C)**

**Figure14: -V<sub>DS</sub> Drain-Source Voltage (V)**

**Figure15: -V<sub>DS</sub> Drain-Source Voltage (V)**

**Figure16: Q<sub>G</sub> Gate Charge (nC)**

**N And P- Channel Enhancement Mode Power MOSSFET**

**Figure17: V<sub>sd</sub> Source-Drain Voltage (V)**

**Figure18: -V<sub>gs</sub> Gate-Source Voltage (V)**

**Figure19: -V<sub>ds</sub> Drain -Source Voltage (V)**

**Figure20: Square Wave Pulse Duration (sec)**

**N And P- Channel Enhancement Mode Power MOSSFET**
**Test Circuit and Waveform(P-Channel):**

**Figure D Gate Charge Test Circuit & Waveforms**

**FigureE Switching Test Circuit & Waveforms**

**Figure F Unclamped Inductive Switching Circuit & Waveforms**

**N And P- Channel Enhancement Mode Power MOSFET**
**PDFN3333 Package Outline Dimensions (Units: mm)**


COMMON DIMENSIONS (UNITS OF MEASURE IS mm)			
	MIN	NORMAL	MAX
A1		0.152 BSC	
A2	0.650	0.750	0.850
A3	0.005	—	0.020
b	0.250	0.300	0.350
D	3.050	3.150	3.250
D1	3.200	3.300	3.400
D2	2.350	2.450	2.550
D3	0.935	1.035	1.135
E1	3.150	3.300	3.450
E	2.950	3.050	3.150
E2	1.635	1.735	1.835
e	0.650 TYPE		
L	0.300	0.400	0.500
$\theta$	12° TYPE		
K1	0.680 REF		
K2	0.380 REF		
L1	0.410 REF		